

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

# **Thermal Characteristics**

TJ

Symbol	Parameter	Value	Units	
P <sub>D</sub>	Power Dissipation	1.8	W	
$R_{ ext{ hetaJA}}$	Thermal Resistance, Junction to Ambient*	80	°C/W	
$R_{ ext{ ext{ ext{ ext{ ext{ ext{ ext{ ext$	Thermal Resistance, Junction to Lead*	26	°C/W	

-65 to +175

\*Device mounted on PCB with 0.2 x 0.2" (5.0 x 5.0 mm) copper pad areas.

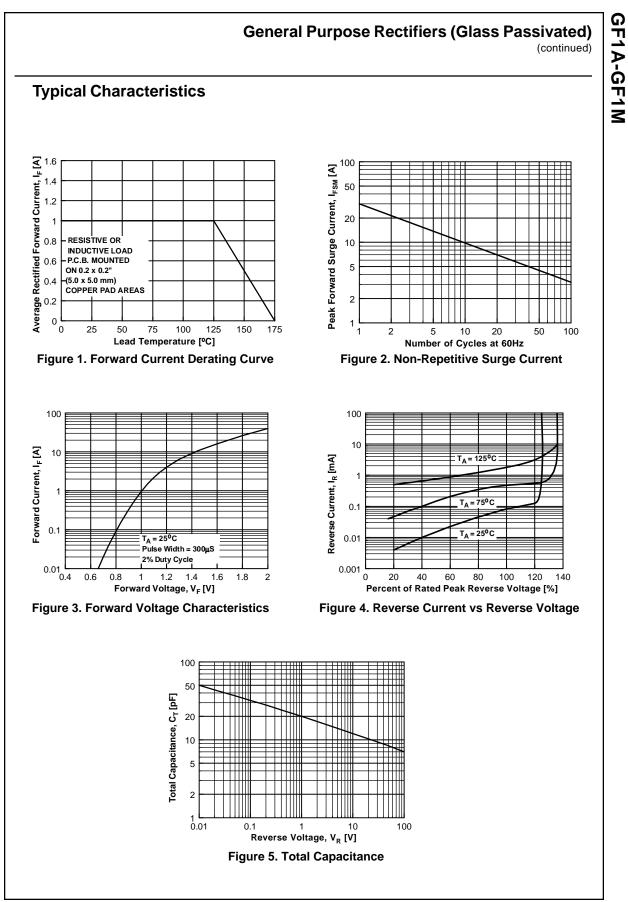
**Operating Junction Temperature** 

## Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Device							Units
		1A	1B	1D	1G	1J	1K	1M		
$V_{F}$	Forward Voltage @ 1.0 A				1.0			1	.2	V
t <sub>rr</sub>	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		2.0						μs	
I <sub>R</sub>		T <sub>A</sub> = 25°C T <sub>A</sub> = 125°C	5.0 50					μΑ μΑ		
C <sub>T</sub>	Total Capacitance $V_{R} = 4.0 V, f = 1.0 MHz$		15					pF		

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°C



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GF1A-GF1M, Rev. G

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